	L Number	Hits	Search Text	DB	Time stamp	
("5143365") or ("638958") or ("6478887") or ("6252298") or ("625298") or ("6252298") or ("6252298") or ("6252298") or ("6252298") or ("6222298") or ("6222	1	11	(("5242855") or ("3918148") or ("6175084")	USPAT;	2004/10/08	11:34
				US-PGPUB		
C						
2						
### and test\$6 and (dic\$4) and magnetic\$6 and eacx20000616 ### adx20000616 ### adx2000061	2	18		- Π Ω DΔΨ •	2004/10/08	00.53
### 88 438/\$.ccls. and align\$6 and test\$6 and (dic\$4) and magnetic\$6 and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (dic\$4) and magnetic\$6 and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (dic\$4) same magnetic\$6) and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (dic\$4) with magnetic\$6) and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (dic\$4) with magnetic\$6) and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (JSPAT) (dic\$4) near magnetic\$6) and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (JSPAT) (dic\$4) near magnetic\$6) and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (JSPAT) (dic\$4) near magnetic\$6) and 8ad<20000616 US-FOFUB; EPO, JPO; DERWENT; IEM TIDB (JSPAT) (J	2				2004/10/08	09.33
Second Color Seco						
188			- Cua 120000010			
(dic\$4) and magnetic\$6 and @ad<20000616 US-DCPUB; EO; JPO; DERNENT; IBM TOB USFAT; 2004/10/03 09:54 2004/10/03 09:55 2004/10/03 09:56 2004/10/03 09				· ·		
Semiconductor and (align% nar test% nar (dic%4) near magnetic%6) and @ad<20000616 Sement; IEM TOB (SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (dic%4) with magnetic%6) and @ad<20000616 SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (dic%4) near magnetic%6) and @ad<20000616 SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (dic%4) near magnetic%6) and @ad<20000616 SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (dic%4) near magnetic%6) and @ad<20000616 SPAT; US-RCPUB; EPO; JPO; DERMENT; IEM TOB (USAT); USAT); USAT; USAT	4	88	438/\$.ccls. and align\$6 and test\$6 and	USPĀT;	2004/10/08	09:54
0			(dic\$4) and magnetic\$6 and @ad<20000616	US-PGPUB;		
S			·			
Semiconductor and (align%6 near test%6 same (dic%4) near magnetic%6) and @ad<20000616 Sements; IBM TOB (dic%4) with magnetic%6) and @ad<20000616 Sements; IBM TOB (dic%4) with magnetic%6) and @ad<20000616 Sements; IBM TOB (dic%4) near magnetic%6) and gad<20000616 Sements; IBM TOB (dic%4) near magnetic%6) and (dic%4) near magnetic%6) near test%6 near test%						
	_	_	420/0		0004/10/00	00 54
Continue	5	0			2004/10/08	09:54
DERWENT; IBM TDB USPAT;			(dic\$4) same magnetic\$6) and @ad<20000616			
0 438/s.ccls. and (align\$6 with test\$6 with (dic\$4) with magnetic\$6) and @ad<20000616 0SPRT; US-PGPUB; EPO; JPO; DERWENT; IBM TOB US-PGPUB; EPO; JPO; DERWENT US-PGPU				·		
0				· ·		
(dic\$4) with magnetic\$6) and @ad<20000616	6	O	438/\$ ccls, and (align\$6 with test\$6 with	_	2004/10/08	09.55
Report	ř	, and the second se		· ·	2004/10/00	07.00
TBM_TDB						
(dic\$4) near magnetic\$6) and @ad<20000616 EPGUB; EPG; JPG; DERWENT; IRM TDB USPĀT; US-FGPUB; EPG; JPG; DERWENT; IRM TDB USPĀT; EPG; JPG; DERWENT USPĀT; EPG; JPG;		*	<u>, </u>		-	
8 0 257/\$.ccls. and (align\$6 near test\$6 near (dic\$4) near magnetic\$6) and @ad<20000616	7	0	438/\$.ccls. and (align\$6 near test\$6 near	USPĀT;	2004/10/08	09:55
8 0 257/\$.ccls. and (align\$6 near test\$6 near (dic\$4) near magnetic\$6) and \$ad<20000616			(dic\$4) near magnetic\$6) and @ad<20000616	US-PGPUB;		
S						
8 0 257/\$.ccls. and (aligns6 near tests6 near (dic\$4) near magnetic\$6) and @ad<20000616 USFĀT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB US-PGPUB; EPG; JPG; DERWENT; US-PGPUB; EPG; JPG; DERWENT; IBM TDB US-PGPUB; EPG; JPG; DERWENT; US-PGPU						
		_	057/0	_	0004/40/00	
9 0 semiconductor and (align\$6 near test\$6 near (dic\$4) near magnetic\$6) and page (dic\$4) near magnetic\$6 and page (dic\$4) an	8	0			2004/10/08	09:55
DERMENT: ILBM TDB USPAT; US-PGPUB; EPO; JPO; DERMENT; ILBM TDB USPAT; US-PGPUB USPAT; USPAT 2002/07/03 08:56 USPAT; EPO; JPO; DERMENT			(dlc\$4) near magnetic\$6) and @ad<20000616			
Semiconductor and (align\$6 near test\$6 near (dic\$4) near magnetic\$6) and near (dic\$4) near magnetic\$6 near (dic\$4) near magnetic\$6 near (dic\$4) near magnetic\$6						
9 0 semiconductor and (align\$6 near test\$6 USPĀT; US-PGPUB; EEO; JPO; DERWENT; IBM TDB 2004/10/08 10:00 10:0				· ·		
near (dic\$4) near magnetic\$6) and	9 1	0	semiconductor and (align\$6 near test\$6	_	2004/10/08	09.56
@ad<20000616					2001, 10, 00	03.00
3						
3				DERWENT;		
and align\$6 and test\$6 and (dic\$4) and magnetic\$6 and @ad<20000616 10 28 438/15,113,110,107,108,114,123,455,456,457, isb_PAT9,460, 45004620468.a0181 and align\$6 and test\$6 and (dic\$4) and magnetic\$6 and @ad<20000616 11 1 ("6165885").PN. USPAT; IBM_TDB USPAT; IBM_TDB USPAT; 2004/10/08 11:34 - 348 (438/15).CCLS. USPAT 2002/07/03 08:58 - 258 (438/13).CCLS. USPAT 2002/07/03 08:58 - 94 (438/110).CCLS. USPAT 2002/07/03 08:58 - 94 (438/110).CCLS. USPAT 2002/07/03 08:58 - 681 438/15,110,113,114.ccls. USPAT 2002/12/19 14:38 - 681 438/15,110,113,114.ccls. and test\$3 - 401 438/15,110,113,114.ccls. and test\$3 - 901 438/15,110,113,114.ccls. and test\$3 - 502/02/04 09:53 - 102/02/04 09:54						
magnetic\$6 and @ad<20000616	3	13			2004/10/08	10:00
DERWENT; IBM TDB 11				•		
10			magnetics6 and @ad<20000616		•	
10				-		
and align\$6 and test\$6 and (dic\$4) and magnetic\$6 and @ad<20000616 11	10	28	438/15-113-110-107-108-114-123-455-456-457-4	_	4 8 M N 4 8 2 N 4 8 8	AA3A1
magnetic\$6 and @ad<20000616 EPO; JPO; DERWENT; IBM_TDB USPAT; IBM_TDB USPAT; IBM_TDB USPAT USPAT 2004/04/08 08:51 USPAT 2002/07/03 08:58 USPAT 2002/07/03 USP		23				TOIDI
DERWENT; IBM TDB USPAT; US-PGPUB USPAT; US-PGPUB USPAT USPAT; EPO; JPO; DERWENT USPAT USPAT 2004/04/08 10:12				· · · · · · · · · · · · · · · · · · ·		
11				DERWENT;		
- 348 (438/15).CCLS. US-PGPUB USPAT 2004/04/08 08:51 - 258 (438/113).CCLS. USPAT 2002/07/03 08:58 - 94 (438/110).CCLS. USPAT 2002/07/03 08:58 - 59 (438/114).CCLS. USPAT 2002/07/03 08:58 - 681 438/15,110,113,114.ccls. USPAT 2002/12/19 14:38 - 401 438/15,110,113,114.ccls. and test\$3 USPAT 2001/08/07 15:09 - 272 (438/15,110,113,114.ccls. and test\$3) and (dice\$4 or cut\$5) - 901 438/15,110,113,114.ccls. USPAT 2001/08/07 15:10 - 460 438/15,110,113,114.ccls. USPAT; EPO; JPO; DERWENT - 460 438/15,110,113,114.ccls. and test\$3 USPAT; EPO; JPO; DERWENT - 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12				_		
- 348 (438/15).CCLS 258 (438/113).CCLS 94 (438/110).CCLS 94 (438/110).CCLS 194 (438/114).CCLS 194 (438/114).CCLS 195 (438/114).CCLS 197 (438/114).CCLS 198 (438/15,110,113,114.ccls 199 (438/15,110,113,114.ccls. and test\$3 USPAT 2002/07/03 08:58 USPAT 2002/12/19 14:38 USPAT 2001/08/07 15:09 USPAT 2001/08/07 15:09 USPAT 2001/08/07 15:09 USPAT 2001/08/07 15:10 USPAT; EPO; JPO; DERWENT USPAT 2004/04/08 10:12	11	1	("6165885").PN.	-	2004/10/08	11:34
- 258 (438/113).CCLS.			(430/15) GGT G		0004/04/05	
- 94 (438/110).CCLS. 59 (438/114).CCLS. 681 438/15,110,113,114.ccls. 681 438/15,110,113,114.ccls. and test\$3 - 401 438/15,110,113,114.ccls. and test\$3 - 272 (438/15,110,113,114.ccls. and test\$3) and (dice\$4 or cut\$5) - 901 438/15,110,113,114.ccls. - 460 438/15,110,113,114.ccls. and test\$3 - 460 438/15,110,113,114.ccls. and test\$3 - 5 (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5) - 5 (("6077757") or ("6335224") or ("6309943") USPAT 2002/04/08 10:12	-					
- 59 (438/114).CCLS 681 438/15,110,113,114.ccls 401 438/15,110,113,114.ccls. and test\$3 - 272 (438/15,110,113,114.ccls. and test\$3) and (dice\$4 or cut\$5) - 901 438/15,110,113,114.ccls 460 438/15,110,113,114.ccls. and test\$3 - 325 (438/15,110,113,114.ccls. and test\$3 - 325 (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5) - 5 (("6077757") or ("6335224") or ("6309943") USPAT - 5 (("6077757") or ("6335224") or ("6309943") USPAT - 2002/07/03 08:58 - 2002/12/19 14:38 - 2001/08/07 15:09 - 2	-					
- 681 438/15,110,113,114.ccls. 401 438/15,110,113,114.ccls. and test\$3 USPAT 2001/08/07 15:09 2001/08/07 15:10 (dice\$4 or cut\$5) - 901 438/15,110,113,114.ccls. 400 438/15,110,113,114.ccls. 4	_ 					
- 401 438/15,110,113,114.ccls. and test\$3 272 (438/15,110,113,114.ccls. and test\$3) and (dice\$4 or cut\$5) - 901 438/15,110,113,114.ccls. - 460 438/15,110,113,114.ccls. and test\$3 - 460 438/15,110,113,114.ccls. and test\$3 - 325 (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5) - 5 (("6077757") or ("6335224") or ("6309943") USPAT - 2001/08/07 15:09 2002/02/04 09:53	_					
- 272 (438/15,110,113,114.ccls. and test\$3) and (dice\$4 or cut\$5) - 901 438/15,110,113,114.ccls. - 460 438/15,110,113,114.ccls. and test\$3 - 325 (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5) - 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12	_					
- 901 438/15,110,113,114.ccls. USPAT; EPO; JPO; DERWENT USPAT; DERWENT USPAT 2004/04/08 10:12	_					
- 460 438/15,110,113,114.ccls. and test\$3						
- 460 438/15,110,113,114.ccls. and test\$3 USPAT; EPO; JPO; DERWENT USPAT 2004/10/06 09:25 ("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12	_	901	438/15,110,113,114.ccls.	-	2002/02/04	09:53
- 460 438/15,110,113,114.ccls. and test\$3 USPAT; EPO; JPO; DERWENT USPAT; (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5) EPO; JPO; DERWENT EPO; JPO; DERWENT USPAT; EPO; JPO; DERWENT USPAT 2004/04/08 10:12						
- 325 (438/15,110,113,114.ccls. and test\$3) and USPAT; 2004/10/06 09:25 (dic\$5 or cut\$5) EPO; JPO; DERWENT - 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12			400/45 440 440 444		000015515	00 = 1
- 325 (438/15,110,113,114.ccls. and test\$3) and USPAT; 2004/10/06 09:25 (dic\$5 or cut\$5) EPO; JPO; DERWENT - 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12	-	460	438/15,110,113,114.ccls. and test\$3	· ·	2002/02/04	09:54
- 325 (438/15,110,113,114.ccls. and test\$3) and USPAT; 2004/10/06 09:25 (dic\$5 or cut\$5) EPO; JPO; DERWENT 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12						
(dic\$5 or cut\$5) EPO; JPO; DERWENT 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12	_	325	(A38/15 110 113 114 color and tootes) and		2004/10/06	00.25
DERWENT 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12	_	323		•	2004/10/00	05:25
- 5 (("6077757") or ("6335224") or ("6309943") USPAT 2004/04/08 10:12			(41040 01 04640)			
	_	5	(("6077757") or ("6335224") or ("6309943")		2004/04/08	10:12
OI ("0303903") OI ("032003/")).PN.			or ("6309909") or ("6326697")).PN.			_ _

-	7	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or	USPAT	2002/02/05 09:49
-	326	("5858815") or ("5137836")).PN (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5)	USPAT; EPO; JPO;	2004/10/07 12:10
-	0	((438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5)) and (magnet\$7 adj	DERWENT USPAT; EPO; JPO;	2002/02/05 08:33
-	170	align\$5) ((438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5)) and (align\$5)	DERWENT USPAT; EPO; JPO;	2002/02/05 08:32
-	2705	magnet\$7 adj align\$5	DERWENT USPAT; EPO; JPO;	2002/02/05 08:56
_	0	(magnet\$7 adj align\$5) and (wafer adj20 dielectric adj tape)	DERWENT USPAT; EPO; JPO;	2002/02/05 08:37
-	0	wafer adj20 dielectric adj tape	DERWENT USPAT; EPO; JPO;	2002/02/05 08:37
-	0	wafer adj dielectric adj tape	DERWENT USPAT; EPO; JPO;	2002/02/05 08:38
-	248	(magnet\$7 adj align\$5) and semiconductor	DERWENT USPAT; EPO; JPO; DERWENT	2002/02/05 08:57
-	0	((magnet\$7 adj align\$5) and ring) and (charged adj slot)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:49
-	0	(magnet\$7 adj align\$5) and (charged adj slot)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:49
_	613	(magnet\$7 adj align\$5) and ring	USPAT; EPO; JPO; DERWENT	2002/02/05 08:50
-	47	((magnet\$7 adj align\$5) and ring) and semiconductor	USPAT; EPO; JPO; DERWENT	2002/02/05 08:51
_	3066	optically adj align\$5	USPAT; EPO; JPO; DERWENT	2002/02/05 08:56
-	612	(optically adj align\$5) and semiconductor	USPAT; EPO; JPO; DERWENT	2002/02/05 08:57
-	8	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836") or ("4781969")).PN.	USPAT	2003/06/02 08:10
-	10260	wood.inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/03 08:13
-	539	wood.inv. and alan	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/03 08:13
-	232	(wood.inv. and alan) and (micron adj technology)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/03 08:14
	,	("6269650") PM	IBM_TDB USPAT	2004/04/06 13:58
-	1 425	' '	USPAT	2002/07/08 08:43
-	331	(438/113).CCLS.	USPAT	2002/07/08 08:57
-	140		USPAT	2002/07/08 08:57
_	90 425	(438/114).CCLS. (438/15).CCLS.	USPAT USPAT	2002/07/08 08:57 2002/07/08 08:43
_	331	(438/13).CCLS.	USPAT	2002/07/08 08:57
<u></u>	140	(438/110).CCLS.	USPAT	2002/07/08 08:57

	90	(438/114).CCLS.	USPAT	2002/07/08 14:32
_	13	1 ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	USPAT	2002/07/08 14:32
	·	or ("4781969") or ("5073840") or ("5696033") or ("5834839") or ("6160714")).PN.		
_	8	(("6309909") or ("5858815") or ("5137836") or ("6077757") or ("6326697") or ("6165885") or ("5834320") or ("4781969")).PN.	USPAT	2002/07/09 09:56
- .	0		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/19 15:00
-	0	<pre>(wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3 same (cut\$4 or dic\$3 or separat\$3)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/19 14:07
-	19	wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/19 14:07
-	0	<pre>(wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/19 14:38
_	963 1212	438/15,110,113,114.ccls. 438/15,110,113,114.ccls.	USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/19 14:38 2002/12/19 14:38
-	0	438/15,110,113,114.ccls. and ((wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/19 14:40
-	9	(wafer adj (dielectric adj (layer or film))) same test\$3	USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/20 08:18
-	13	(("5834839") or ("6389689") or ("6160714") or ("5977629") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("5796170") or ("4781969") or ("5073840") or ("5696033")).PN.	USPAT	2002/12/19 15:19
_	85	wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/20 08:42
_	 78	<pre>(wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3)) and semiconductor</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/20 09:38
_	348	(wafer same (dielectric adj (layer or film))) same test\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/20 09:35

		·		
-	322	<pre>((wafer same (dielectric adj (layer or film))) same test\$3) and semiconductor</pre>	USPAT; US-PGPUB;	2002/12/20 09:38
		IIIm/// Same cestys / and semiconductor	EPO; JPO;	
			DERWENT;	
1_	98	(((wafer same (dielectric adj (layer or	IBM_TDB USPAT;	2002/12/20 09:39
	30	film))) same test\$3) and semiconductor)	US-PGPUB;	2002/12/20 05.55
		and (cut\$3 or dic\$3)	EPO; JPO;	
			DERWENT; IBM TDB	÷
_	1	("6424023").PN.	USPAT	2002/12/20 10:24
_	3	(("5897337") or ("5858815") or	USPAT	2002/12/23 11:53
		("6389689")).PN.	TICDAM.	2002/12/23 11:53
-	9187	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/12/23 11:53
		semiconductor	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
-	4418	(((balls adj grid adj arrays) or (BGA))	USPAT;	2003/05/20 08:02
		and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	
ļ		separat\$5)	EPO; JPO; DERWENT;	
			IBM_TDB	
-	4476		USPAT;	2003/05/20 08:04
¥ :		and semiconductor) and (dic\$4 or cut\$4 or separat\$5 or saw\$4)	US-PGPUB; EPO; JPO;	
		Soparation of Santin	DERWENT;	
	0.5.5		IBM_TDB	0000/05/00 00 04
-	955	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or	USPAT; US-PGPUB;	2003/05/20 08:04
		separat\$5)) and (metal adj (film or	EPO; JPO;	
		layer))	DERWENT;	
_	970	((((balls adj grid adj arrays) or (BGA))	IBM_TDB USPAT;	2003/05/20 08:04
]	and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	2000,00,20 00101
		separat\$5 or saw\$4)) and (metal adj (film	EPO; JPO;	
		or layer))	DERWENT; IBM TDB	-
_	1		US-PGPUB	2003/05/20 08:12
-	472		USPAT;	2003/05/20 08:52
		(attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor	US-PGPUB; EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)	DERWENT;	
	233	(wafer and (metal adj (film or layer)) and	IBM_TDB USPAT;	2004/01/12 08:09
	233	(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	2004/01/12 00.09
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616	DERWENT; IBM TDB	
-	212		USPAT;	2003/05/21 08:23
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or	EPO; JPO; DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	·
	200	or cut\$6 or saw\$5)		2002/05/20 20 25
_	206	((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj	USPAT; US-PGPUB;	2003/05/20 09:06
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT; IBM TDB	
		separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6)	TOM_IND	
-	1	(((wafer adj semiconductor) same (metal	USPAT;	2003/05/20 10:06
		adj (film or layer)) same (attach\$5 or bond\$4) same ((balls adj grid adj arrays)	US-PGPUB; EPO; JPO;	
		or (BGA)) same (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) same (dic\$5 or cut\$6 or	IBM_TDB	
<u></u>		saw\$5)) and @ad<=20000616		<u> </u>

-	212	((wafer and (metal adj (film or layer))	USPAT;	2003/05/21	09:00
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	1	
		grid adj arrays) or (BGA)) and	EPO; JPO;		
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB		
	170	or cut\$6 or saw\$5)	, uana	2002/05/01	00 04
-	172	(((wafer and (metal adj (film or layer))	USPAT;	2003/05/21	09:24
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB; EPO; JPO;		
		grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB		
		or cut\$6 or saw\$5)) and dic\$5	1014_100		
_	92		USPAT;	2003/05/21	09:35
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	2000,00,21	03.00
		grid adj arrays) or (BGA)) and	EPO; JPO;		
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB		
		or cut\$6 or saw\$5)) and (dicing or diced)	_		
_	70		USPAT;	2003/05/21	09:36
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;		
		grid adj arrays) or (BGA)) and	EPO; JPO;		
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB		
		or cut\$6 or saw\$5)) and (dicing or			
	30	diced)) and (individual\$3 or each)	tionam -	2002/05/21	00-20
	70		USPAT;	2003/05/21	U9:36
		and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and	US-PGPUB; EPO; JPO;		
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB		
		or cut\$6 or saw\$5)) and (dicing or	1511_155		
		diced)) and (individual\$3)			
_	6		USPAT;	2003/05/21	09:37
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;		
		grid adj arrays) or (BGA)) and	EPO; JPO;		
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB		
		or cut\$6 or saw\$5)) and (dicing or			
		diced)) and (individual\$3 adj device)			
_	2		USPAT	2004/01/12	
-	241	(wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid	USPAT; US-PGPUB;	2004/01/12	08:10
		adj arrays) or ("BGA")) and semiconductor	EPO; JPO;		
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;		
		@ad<=20000616	IBM TDB		
_	1	((wafer same (metal adj (film or layer))	USPAT;	2003/10/23	10:36
		same (attach\$5 or bond\$4) same ((balls adj	US-PGPUB;		
		grid adj arrays) or ("BGA")). same	EPO; JPO;		
		semiconductor same (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5))) and @ad<=20000616	IBM_TDB	· _	
_	2	(("6153448") or ("20020011859")).PN.	USPAT;	2003/10/24	12:35
		/ / II C F A A A A A A A A A	US-PGPUB	0000 (55.5)	
-	4	, , , , , , , , , , , , , , , , , , ,	USPAT;	2003/10/24	14:07
		("6064217") or ("5475317")).PN.	US-PGPUB	2004/01/10	00 4 4
-	3	(("6344401") or ("6165885") or ("5834320")).PN.	USPAT	2004/01/12	U9:14
_	244	("5834320")).PN. (wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12	00.02
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	2004/01/12	00.03
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;		. [
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;		
		@ad<=20000616	IBM TDB		
-	244		USPĀT;	2004/04/06	08:33
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;		
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;		
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;		
		@ad<=20000616	IBM_TDB	000115115	00
-	166		USPAT;	2004/01/12	08:05
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;		
		<pre>grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or</pre>	EPO; JPO;		
		semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and	DERWENT; IBM TDB		
		align\$6	12.1_125		
	I			L	

- 688 (438/455).CCLS. (438/455).CCLS. (438/455).CCLS. (USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB 12 438/455,456,457,458,459,460,461,462,464.cclsUSPAT; and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and (balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 97 438/\$.ccls. and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=2000616 348 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or berwent; separat\$5)) and @ad<=20000616 DERWENT; separat\$5)) and @ad<=20000616 DERWENT; separat\$5)) and @ad<=20000616	06 09:26 06 09:23
BPO; JPO; DERWENT; IBM_TDB 2004/10/0	06 09:23
DERWENT; IBM_TDB 12 438/455,456,457,458,459,460,461,462,464.cclsUSPAT; and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj ePO; JPO; grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 97 438/\$.ccls. and (wafer and (metal adj USPAT; (film or layer)) and (attach\$5 or bond\$4) us-PGPUB; and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 - 348 (wafer and ((metal or conductive) adj USPAT; (film or layer)) and (attach\$5 or bond\$4) us-PGPUB; and ((balls adj grid adj arrays) or (BGA)) us-PGPUB; and ((balls adj grid adj arrays) or (BGA)) and (balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT;	06 09:23
TBM_TDB 12 438/455,456,457,458,459,460,461,462,464.ccls USPAT; and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 97 438/\$.ccls. and (wafer and (metal adj USPAT; (film or layer)) and (attach\$5 or bond\$4) US-PGPUB; and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 - 348 (wafer and ((metal or conductive) adj (WSPAT; (film or layer)) and (attach\$5 or bond\$4) US-PGPUB; and ((balls adj grid adj arrays) or (BGA)) US-PGPUB; and ((balls adj grid adj arrays) or (BGA)) EPO; JPO; and semiconductor and (dic\$4 or cut\$4 or DERWENT;	06 09:23
- 12 438/455,456,457,458,459,460,461,462,464.ccls USPAT; and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and (attach\$5 or bond\$4) and (DSPAT; (film or layer)) and (attach\$5 or bond\$4) and (USPAT; (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and (ad<=20000616 and (Wafer and (metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and (DSPAT; (film or layer)) and (attach\$5 or bond\$4) and (USPAT; (film or layer)) and (attach\$5 or bond\$4) and (USPAT; (film or layer)) and (attach\$5 or bond\$4) and (DSPAT; (film or layer)) and (attach\$5 or bond\$4) and (USPAT; and (balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT;	06 09:23
and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 97 438/\$.ccls. and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 348 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and (balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT;	06 09:23
and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 97 438/\$.ccls. and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 - 348 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 97 438/\$.ccls. and (wafer and (metal adj (105) (film or layer)) and (attach\$5 or bond\$4) (105) ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 - 348 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) (USPAT; (ISPAT); (ISPAT)	
cut\$4 or separat\$5)) and @ad<=20000616 97 438/\$.ccls. and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 - 348 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT; DERWENT; DERWENT; DERWENT;	
- 97 438/\$.ccls. and (wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) US-PGPUB; and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 - 348 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) US-PGPUB; and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
(film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT; 2004/04/04/05 DERWENT;	
and ((balls adj grid adj arrays) or ("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT; DERWENT; DERWENT;	08:36
("BGA")) and (dic\$4 or cut\$4 or separat\$5)) and (ad<=20000616 - 348 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) US-PGPUB; and ((balls adj grid adj arrays) or (BGA)) EPO; JPO; and semiconductor and (dic\$4 or cut\$4 or DERWENT;	08:36
separat\$5)) and @ad<=20000616 (wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or DERWENT;	08:3
- 348 (wafer and ((metal or conductive) adj USPĀT; 2004/04/0 (film or layer)) and (attach\$5 or bond\$4) US-PGPUB; and ((balls adj grid adj arrays) or (BGA)) EPO; JPO; and semiconductor and (dic\$4 or cut\$4 or DERWENT;	06 08:36
(film or layer)) and (attach\$5 or bond\$4) US-PGPUB; and ((balls adj grid adj arrays) or (BGA)) EPO; JPO; and semiconductor and (dic\$4 or cut\$4 or DERWENT;	·
and ((balls adj grid adj arrays) or (BGA)) EPO; JPO; and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
separat\$5)) and @ad<=20000616	
- 229 ((wafer and ((metal or conductive) adj USPĀT; 2004/04/0	08:36
(film or layer)) and (attach\$5 or bond\$4) US-PGPUB;	
and ((balls adj grid adj arrays) or (BGA)) EPO; JPO;	
and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
separat\$5)) and @ad<=20000616) and IBM_TDB	
test\$4	م
- 85 (((wafer and ((metal or conductive) adj USPAT; 2004/04/0	08:37
(film or layer)) and (attach\$5 or bond\$4) US-PGPUB;	
and ((balls adj grid adj arrays) or (BGA)) EPO; JPO;	
and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
separat\$5)) and @ad<=20000616) and IBM_TDB	
test\$4) and (input same output) - 86 (((wafer and ((metal or conductive) adj USPAT; 2004/04/04/04/04/04/04/04/04/04/04/04/04/	16 00.47
(film or layer)) and (attach\$5 or bond\$4) US-PGPUB;	70 00:44
and ((balls adj grid adj arrays) or (BGA)) EPO; JPO;	
and (balls adj glid adj allays) of (bgA), Elo, blo, and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
separat\$5)) and @ad<=20000616) and IBM TDB	
test\$4) and (input and output)	
- 78 ((((wafer and ((metal or conductive) adj USPAT; 2004/04/0	06 11:21
(film or layer)) and (attach\$5 or bond\$4) US-PGPUB;	
and ((balls adj grid adj arrays) or (BGA)) EPO; JPO;	
and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
separat\$5)) and @ad<=20000616) and IBM_TDB	
test\$4) and (input and output)) and (cut\$5	
or dic\$6)	
- 24 (((((wafer and ((metal or conductive) adj USPAT; 2004/04/0)6 11:23
(film or layer)) and (attach\$5 or bond\$4) US-PGPUB;	
and ((balls adj grid adj arrays) or (BGA)) EPO; JPO;	
and semiconductor and (dic\$4 or cut\$4 or DERWENT;	
separat\$5)) and @ad<=20000616) and IBM_TDB	
test\$4) and (input and output)) and (cut\$5 or dic\$6)) and (conductive adj trace)	
- 5 (("5858815") or ("4781969") or ("5073840") USPAT 2004/04/0	18 13.50
or ("5770032") or ("5817535")).PN.	,, 13.36
- 10 (("5073840") or ("5817535") or ("5858815") USPAT 2004/04/0)8 13-20
or ("6426642") or ("6214716") or	
("6188232") or ("6163956") or ("6150193")	
or ("6060891") or ("6004867")).PN.	
- 10 (("5073840" "5817535" "5858815" "6426642" USPAT; 2004/04/0	09:30
"6214716" "6188232" "6163956" "6150193" US-PGPUB;	
"6060891" "6004867").pn.) and test\$5 and EPO; JPO;	
(cut\$5 or dic\$6 or seperat\$5 or saw\$4) DERWENT;	
IBM_TDB	
- 6 ((("5073840" "5817535" "5858815" "6426642" USPĀT; 2004/04/	
"6214716" "6188232" "6163956" "6150193" US-PGPUB;	09:30
"6060891" "6004867") pn.) and test\$5 and EPO; JPO;)8 09:30
(cut\$5 or dic\$6 or seperat\$5 or saw\$4)) DERWENT;)8 09:3(
and cut\$6 IBM_TDB	09:30

	1134	438/\$.ccls. and test\$6 and (dic\$4) and	USPAT;	2004/10/06 09:25
_	1134	@ad<20000616	US-PGPUB;	2004/10/00 09.23
		640/20000010		
			EPO; JPO;	
			DERWENT;	
	01.60	057/0 ==1= ==4 ==+00 ==4 (3)=04) ==4	IBM_TDB	2004/10/06 00:05
_	2169	257/\$.ccls. and test\$6 and (dic\$4) and	USPAT;	2004/10/06 09:25
·		@ad<20000616	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	203		USPAT;	2004/10/06 09:25
1		(dic\$4) and @ad<20000616	EPO; JPO;	
			DERWENT	
ļ -	199			2004/10/08 09:53
		and test\$6 and (dic\$4) and @ad<20000616	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	("6261919").PN.	USPAT;	2004/10/06 13:56
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	2	("6429530").PN.	USPAT;	2004/10/07 08:13
			US-PGPUB;	
			EPO; JPO;	
	*		DERWENT;	
			IBM TDB	
_	7	(("6163956") or ("6153448") or ("6064217")	USPAT;	2004/10/07 10:04
		or ("6344401") or ("4781969") or	US-PGPUB	
		("5137836") or ("20010052642")).PN.		
_	1		USPAT;	2004/10/07 13:52
	_	, , , , , , , , , , , , , , , , , , , ,	US-PGPUB	=====================================
	1	("5897334").PN.	USPAT;	2004/10/07 13:52
'	_	(303.331 / 1111.	US-PGPUB	1001, 10, 0, 10.02
		<u> </u>	1 OO LGEOD	l